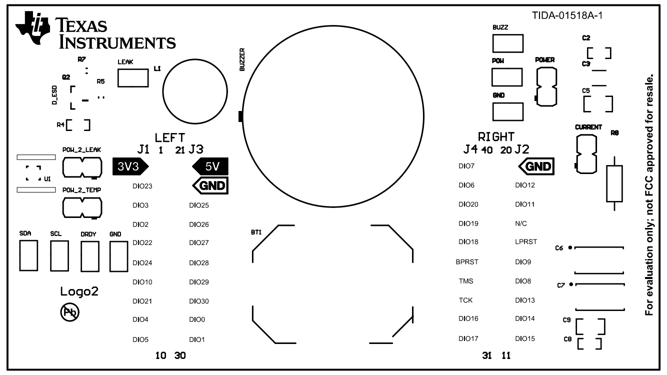
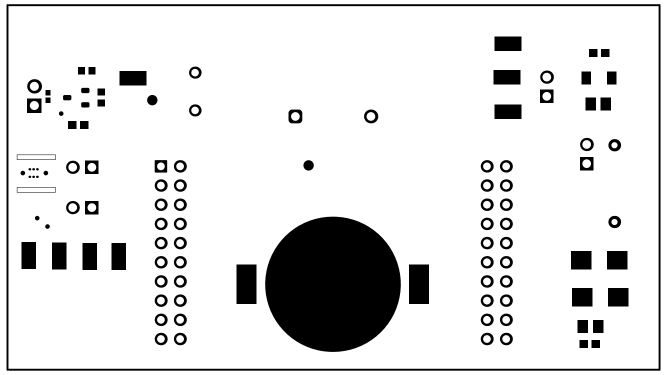
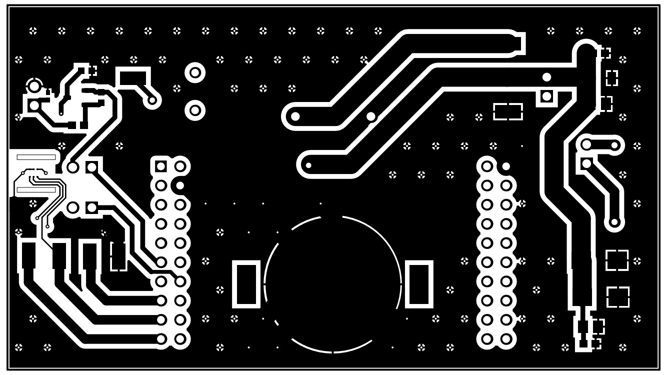


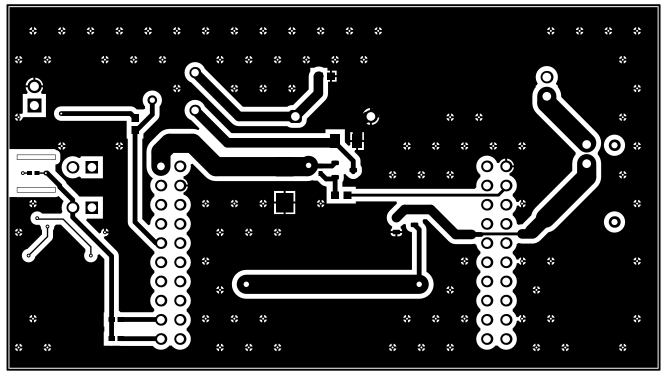
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:	TIDA-01518	REV:	A	SVN REV:	Not In VersionControl
LAYER NAME = Top Overlay	TID #:	TIDA-01518				
PLOT NAME = Top Overlay	GENERATED :	8/4/2017	11:00:25 AM		TEXAS INSTRUMENTS	



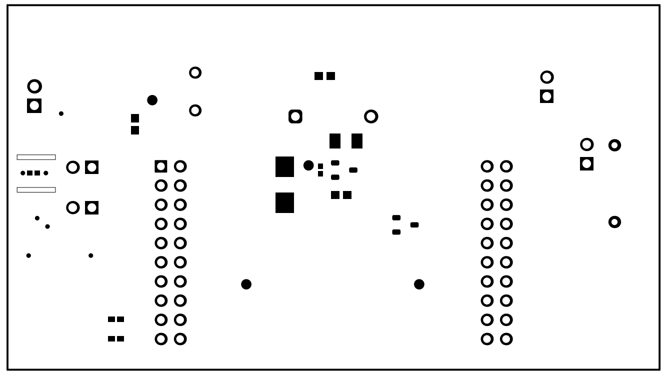
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01518	REV: A	SVN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: TIDA-01518		
PLOT NAME = Top Solder Mask	GENERATED : 8/4/2017 11:00:27 AM		TEXAS INSTRUMENTS



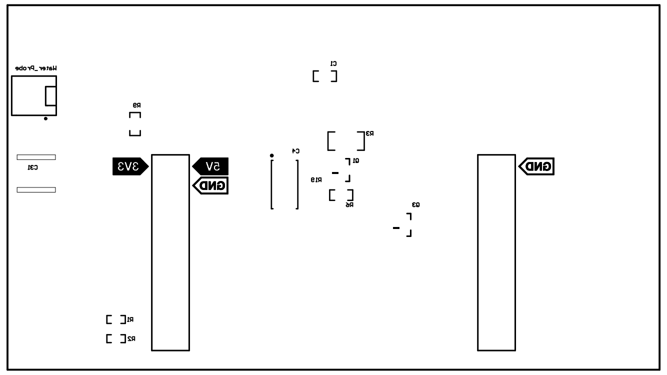
ALL ARTWORK VIEWED FROM TOP SIDE		BOARD #: TIDA-01518	REV: A	SVN REV: Not In VersionControl	
LAYER NAME =	Top Layer	TID #: TIDA-01518			
PLOT NAME =	Top Layer	GENERATED :	8/4/2017	11:00:28 AM	TEXAS INSTRUMENTS



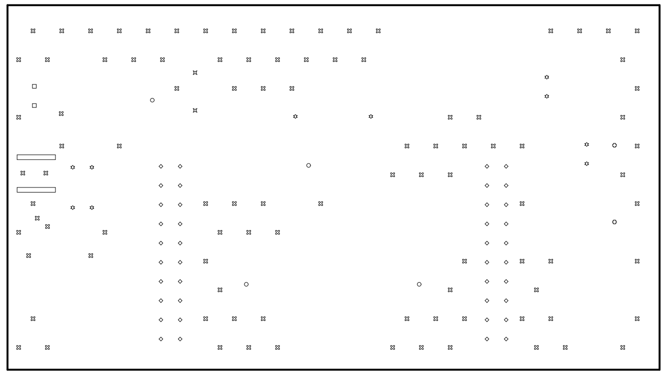
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01518	REV: A	SVN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: TIDA-01518		
PLOT NAME = Bottom Layer	GENERATED : 8/4/2017 11:00:30 AM		TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE		BOARD #:	TIDA-01518	REV:	A	SVN REV:	Not In VersionControl
LAYER NAME =	Bottom Solder	TID #:	TIDA-01518				
PLOT NAME =	Bottom Solder Mask	GENERATED :	8/4/2017	11:00:31 AM		TEXAS INSTRUMENTS	

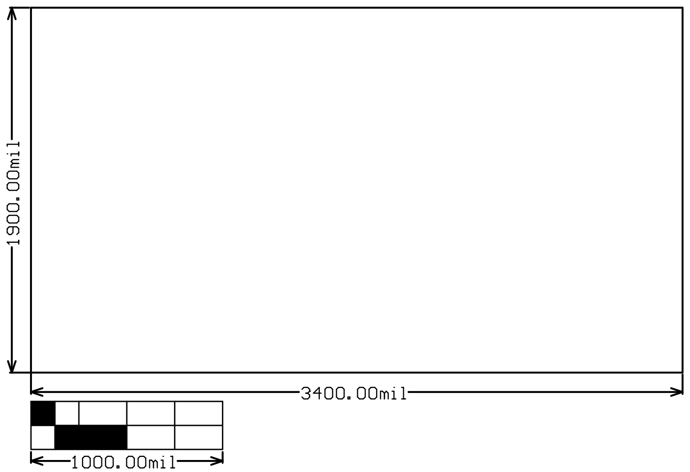


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01518	REV: A	SVN REV: Not In VersionControl	
LAYER NAME = Bottom Overlay	TID #: TIDA-01518			
PLOT NAME = Bottom Overlay	GENERATED : 8/4/2017	11:00:33 AM		TEXAS INSTRUMENTS



Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
⊠	98	10.00mil (0.254mm)	PTH	Round	Top Layer - Bottom Layer	
○	4	28.00mil (0.711mm)	PTH	Round	Top Layer - Bottom Layer	
✚	2	32.00mil (0.813mm)	PTH	Round	Top Layer - Bottom Layer	
✦	2	39.37mil (1.000mm)	PTH	Round	Top Layer - Bottom Layer	
◇	40	40.16mil (1.020mm)	PTH	Round	Top Layer - Bottom Layer	
✡	10	45.28mil (1.150mm)	PTH	Round	Top Layer - Bottom Layer	
□	2	47.24mil (1.200mm)	PTH	Round	Top Layer - Bottom Layer	
	158 Total					

ALL ARTWORK VIEWED FROM TOP SIDE		BOARD #:	TIDA-01518	REV: A	SVN REV:	Not In VersionControl
LAYER NAME =	Drill Drawing	TID #:	TIDA-01518			
PLOT NAME =	Drill Drawing	GENERATED :	8/4/2017	11:00:34 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01518	REV: A	SVN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: TIDA-01518		
PLOT NAME = Board Dimensions	GENERATED : 8/4/2017 11:00:36 AM		TEXAS INSTRUMENTS

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